

# ECSS-Q-HB-60-02

## **“Techniques for Radiation Effects Mitigation in ASICs and FPGAs”**

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Microelectronics Section  
ESTEC  
17/09/2014

- Handbook goals & scope
- ECSS context
- History of this Handbook
- General structure:
- walk through the contents
- The Working Group review and status

## compilation of

techniques to mitigate effects of radiation in integrated circuits (ICs), ASICs & FPGAs

## Handbook intended users

Engineers doing selection, use or development of ASIC/FPGA to be used in radiation environment.

techniques **grouped** according to the different stages (levels) of an IC development flow

- manufacturing processes
- transistor-level design and layout
- standard logic-cell libraries
- rad hard memory cells
- analogue, digital or mixed-signal IC / SoC designs
- SW and off-chip HW mitigations

## In addition,

- overview of the space radiation environment and its effects in semiconductor devices
- how to validate the mitigation techniques
- general guidelines for selecting techniques, examples of typical scenarios

## Guidelines and references, not requirements

# Deciphering the handbook coded name



**Space product  
assurance  
(branch “Q”)**

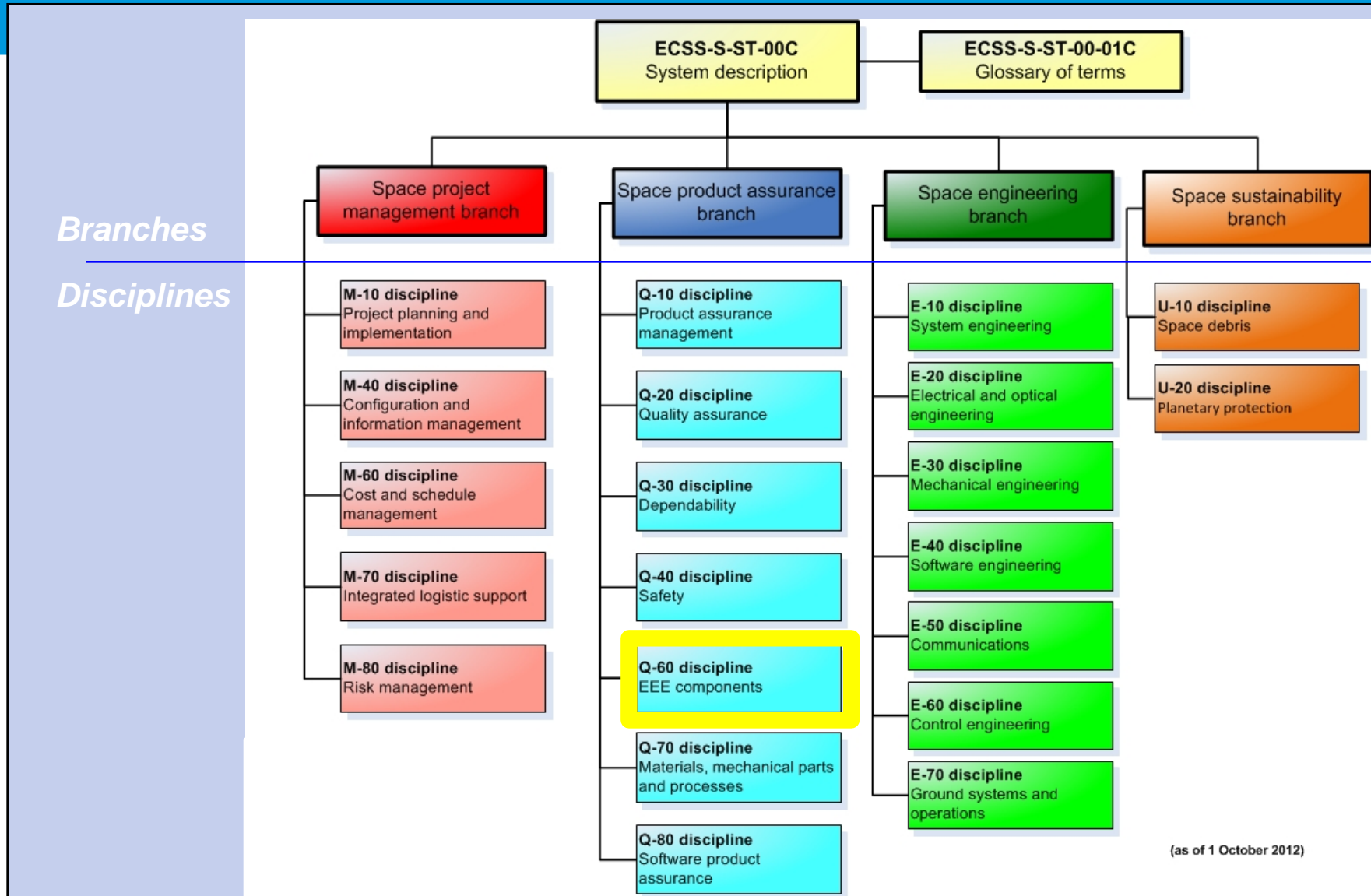
**ECSS-Q-HB-60-02**

**Handbook**

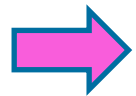
**EEE  
Components  
(discipline “60”)**

**“Techniques for  
Radiation Effects  
Mitigation in  
ASICs and  
FPGAs”**

# ECSS documentation structure

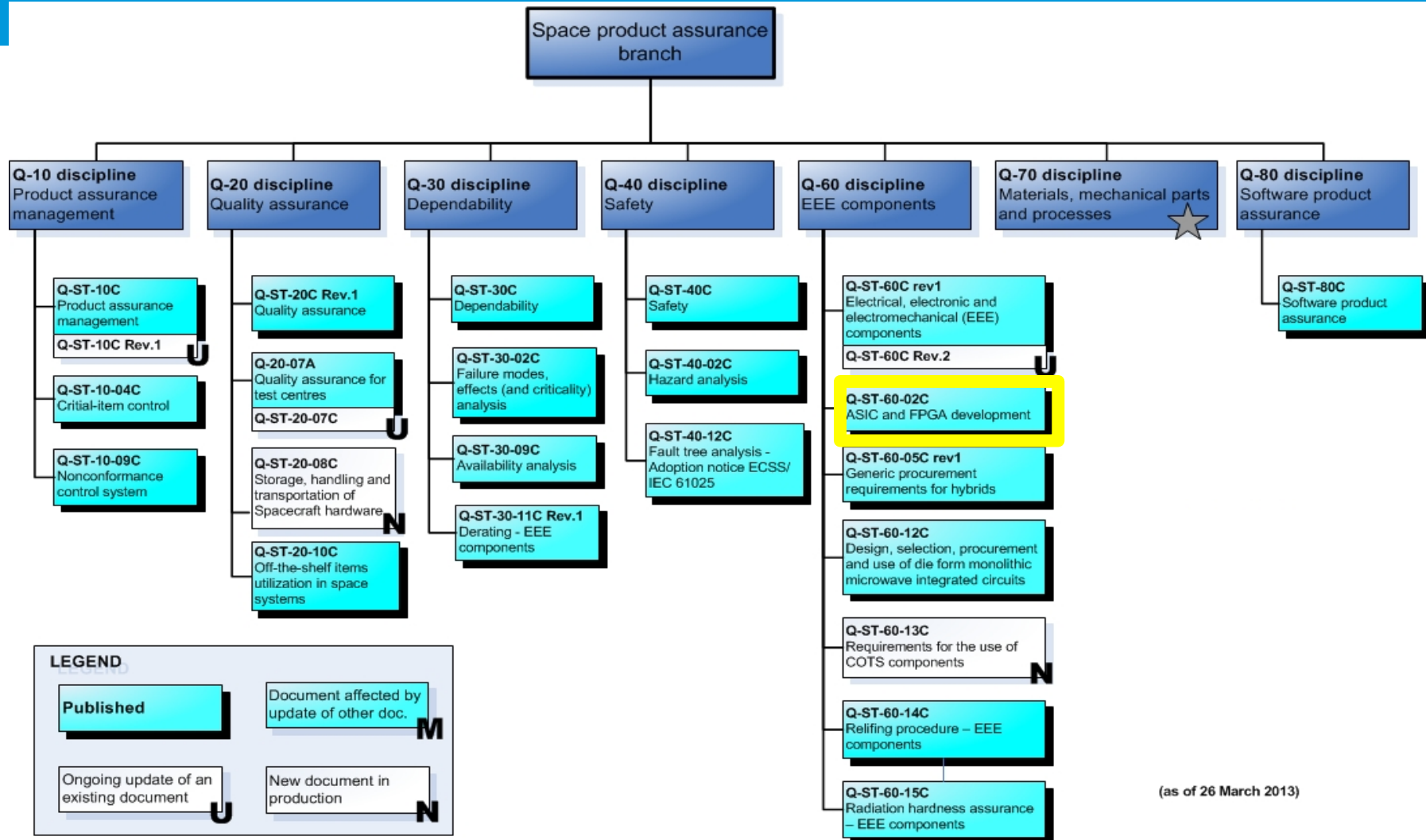


# ECSS types of documents

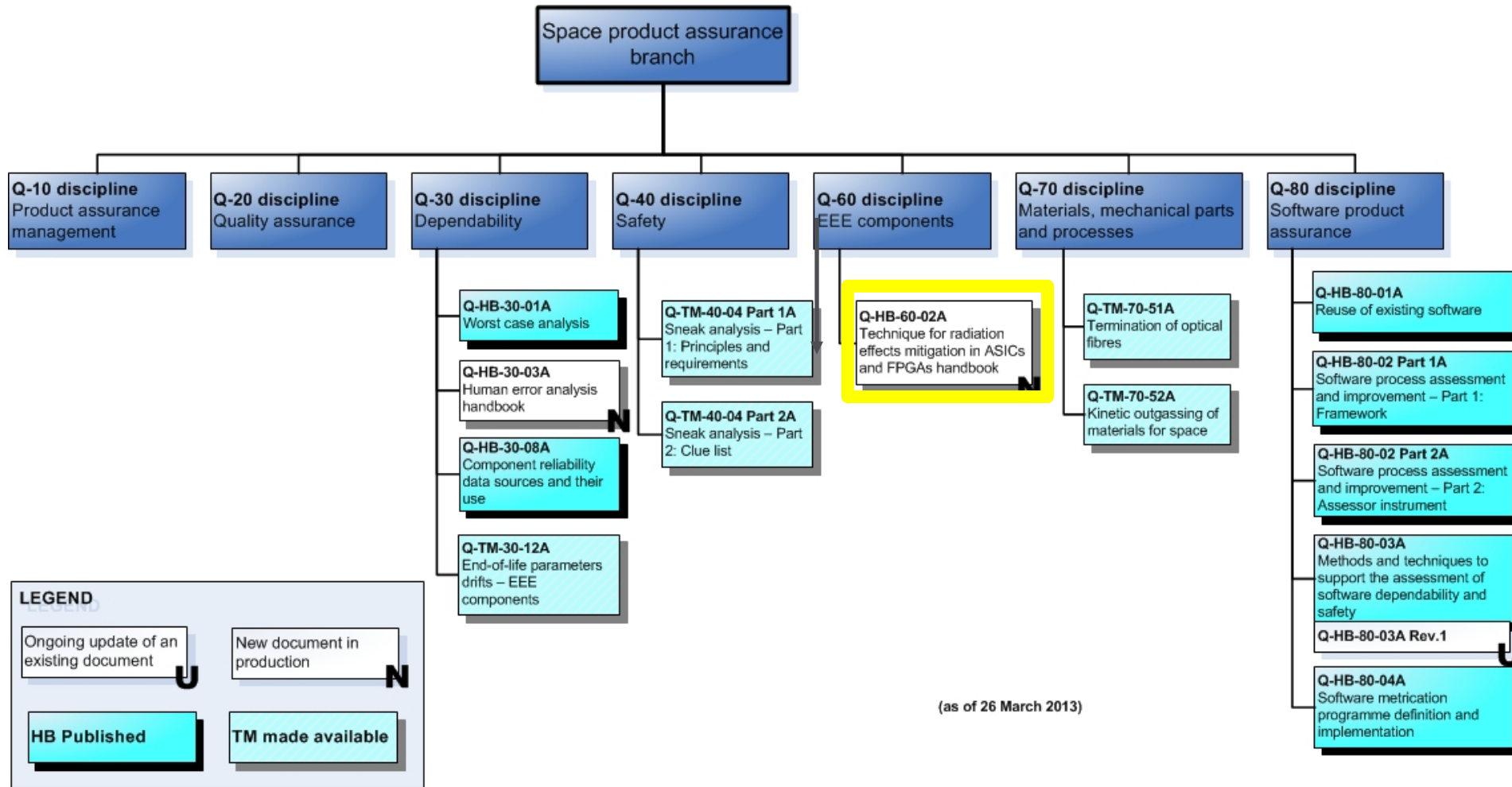


<b>standards</b>	for direct use in invitation to tender and business agreements
<b>handbooks</b>	non-normative documents providing guidelines and/or collection of data
<b>technical memoranda</b>	non-normative documents providing useful info or data not yet mature for a standard or handbook

# ECSS Q branch available standards



# ECSS Q branch available Handbooks and Technical Memoranda





# History of ECSS-Q-HB-60-02



**1998** : first contract to prepare an ECSS Std for ASIC development (TESAT(D))

**2007/07**: ECSS-Q-60-02: "ASIC and FPGA development" **standard** released

**2008/07**: ECSS-Q-**ST**-60-02: "ASIC and FPGA development" name changed



**2010/03**: contract KO to develop 1st ECSS-Q-**HB**-60-02 draft : "Techniques for Radiation Effects Mitigation in ASICs and FPGAs" by **TIMA**(F) et al.

**2010/09**: workshop on the topic at ESTEC

**2011/12**: Final presentation (version 6 of the HB draft) with training at ESTEC

**2012/02**: Final revision to the HB (version 7), with inputs from TIMA & ESTEC

**2013/10**: "ECSS Working Group" KO to improve the 1st HB draft for future ECSS public review

**2014** : ECSS Working Group preparing a new, improved HB draft for ...

**2015/03**: ECSS-Q-HB-60-02 release for ECSS “**public review**”

**2015/Q3**: ECSS-Q-HB-60-02 **final release** as a new ECSS handbook

# Who worked in the ECSS-Q-HB-60-02 ?



First HB draft put together by **TIMA (F)**, under **ESA** contract, with inputs from:

- M. Alles, **University of Vanderbilt (USA)** (process and layout level)
- D. Loveless, University of Vanderbilt (analogue & mixed-signal circuits)
- M. Nicolaidis, **TIMA(F)** laboratory (digital circuits)
- F. L. Kastensmidt, **Universidade Federal do Rio Grande do Sul(Brazil)** (digital circuits & FPGAs)
- M. Violante, **Politecnico di Torino(I)** (embedded software)
- M. Pignol, **CNES(F)** (system architecture)

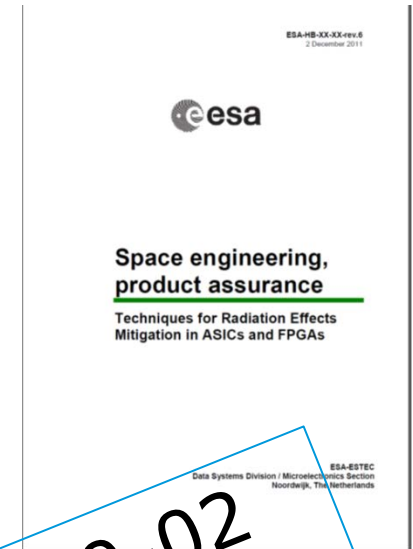
Final HB version (expected for 2015 Q3) by the ECSS WG will include inputs/corrections from experts in **ESA, Thales, AirbusDS, RUAG, OHB, CNES(F), CERN(CH) and IMEC(B)**

**Over 300 citations** of industry, academia, vendors and agencies worldwide

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	8 Layout
	9 Analogue circuits
	10 Digital circuits
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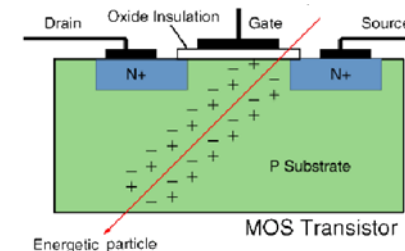
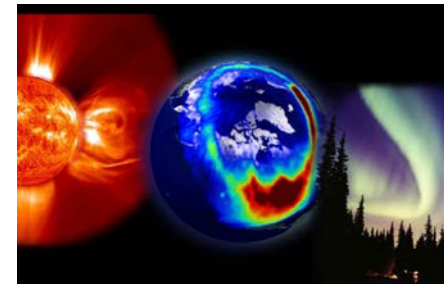
ECSS-Q-HB-60-02  
Version 7  
(Feb 2012)

- a. Scope
- b. Table of Mit. Techniques vs. Rad Effects they
- c. Mitigation techniques concept descriptions, how to implement it
- d. Examples, Figures
- e. Available Test Data (simulations, radiation testing, in-flight)
- f. Added value (efficiency)
- g. Known issues (Weaknesses, elements to be considered)
- h. ID card
  - IC family
  - Abstraction level
  - Pros
  - Cons
  - Mitigated effects
  - Validation Methods
  - Automation tools
  - Vendor solutions

# ECSS-Q-HB-60-02: the first chapters

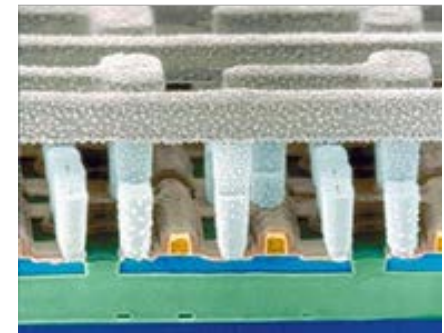
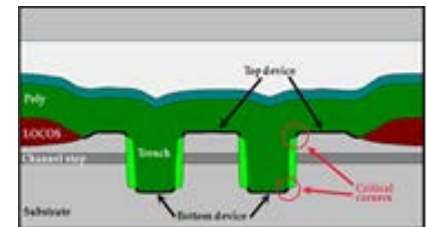


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  - 7.3.3 Triple wells
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- 7.4 Technology scaling and radiation effects
  - 7.4.1 Effects of technology scaling on TID sensitivity
  - 7.4.2 Effects of technology scaling on SEE sensitivity



## 8 Layout

8.1 Scope

8.2 Table of effects vs mitigation techniques

8.3 Mitigation techniques

8.3.1 Enclosed Layout Transistor

8.3.2 Contacts and guard rings

8.4 Radiation-hardened libraries

8.4.1 IMEC Design Against Radiation Effects library

8.4.2 CERN 0.24  $\mu\text{m}$  radiation hardened library

8.4.3 BAE 0.15  $\mu\text{m}$  radiation hardened library

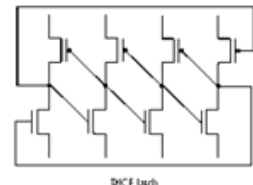
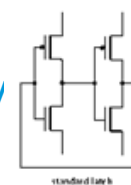
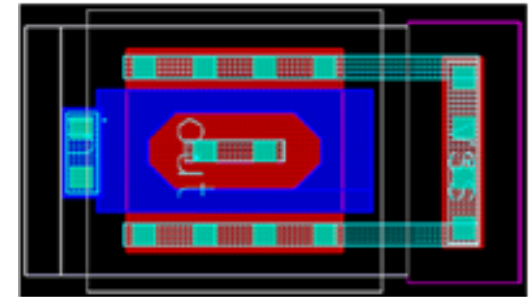
8.4.4 Ramon Chips 0.18  $\mu\text{m}$  and 0.13  $\mu\text{m}$  radiation hardened libraries

8.4.5 Aeroflex 600, 250, 130 and 90 nm radiation hardened libraries

8.4.6 Atmel MH1RT 0.35  $\mu\text{m}$  and ATC18RHA 0.18  $\mu\text{m}$  CMOS radiation hardened libraries

8.4.7 ATK 0.35  $\mu\text{m}$  radiation hardened cell library

8.4.8 ST Microelectronics radiation hardened library





## 9 Analogue circuits

9.1 Scope

9.2 Table of effects vs mitigation techniques

9.3 Mitigation techniques

9.3.1 Node Separation and Interdigitation

9.3.2 Analog Redundancy (Averaging)

9.3.3 Resistive Decoupling

9.3.4 Filtering

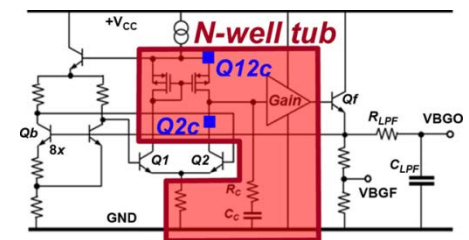
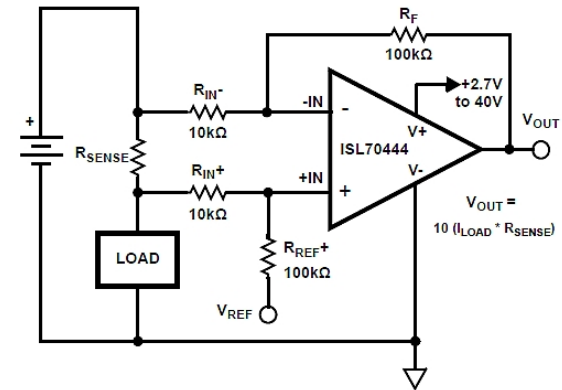
9.3.5 Modifications in Bandwidth, Gain, Operating Speed, and Current Drive

9.3.6 Reduction of Window of Vulnerability

9.3.7 Reduction of High Impedance Nodes

9.3.8 Differential Design

9.3.9 Dual Path Hardening



## 10 Digital circuits

### 10.3.1

#### Spatial redundancy

#### 10.3.1.1

Duplex architectures

#### 10.3.1.2

TMR architectures

#### 10.3.1.2.1

Full, global, functional, large-grain TMR

#### 10.3.1.2.2

Block, local TMR

### 10.3.2

#### Temporal redundancy

#### 10.3.2.1

Triple Temporal Redundancy combined with spatial redundancy

#### 10.3.2.2

Minimal level sensitive latch

#### 10.3.2.3

Dual Temporal Redundancy

### 10.3.3

#### Fail-Safe Finite State Machines

### 10.3.4

#### Memory Block mitigation (bit interleaving, EDAC)

### 10.3.5

#### Error Correction Codes

#### 10.3.5.1

Parity check

#### 10.3.5.2

M-of-N code

#### 10.3.5.3

Cyclic Redundancy Check

#### 10.3.5.4

BCH codes

#### 10.3.5.5

Hamming codes

#### 10.3.5.6

SEC-DED codes

#### 10.3.5.7

Reed-Solomon codes

#### 10.3.5.8

Arithmetic codes

### 10.3.6

#### Selective use of logic cells available in the vendor-provided library

#### 10.3.6.1

Rad Hard Flip-Flops

#### 10.3.6.2

High drive (larger transistors) cells

### 10.3.7

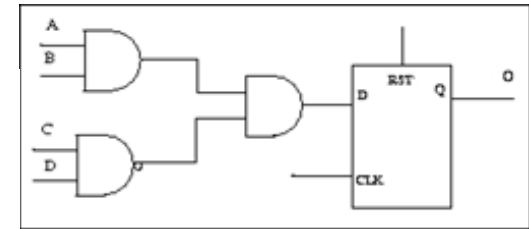
#### Buffers to filter SET pulses in data paths

### 10.3.8

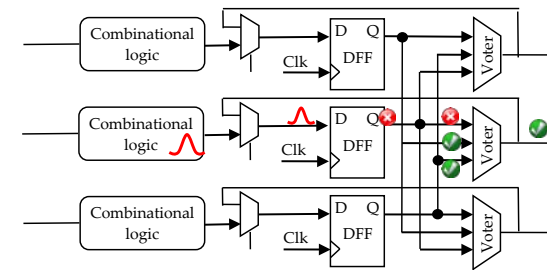
#### Watchdog timers

### 10.3.9

#### Mitigation of FFT and FIR filters



b)

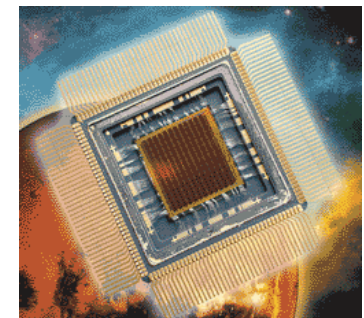


## 12 Field Programmable Gate Arrays

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- 12.2 Table of effects vs mitigation techniques
- 12.3 Mitigation techniques
  - 12.3.1 Reliability-Oriented Place and Route Algorithms
  - 12.3.2 Scrubbing
  - 12.3.3 Additional voters in TMR datapaths (domain crossing events)
  - 12.3.4 FPGA TMR specific tools: Xilinx XTMR



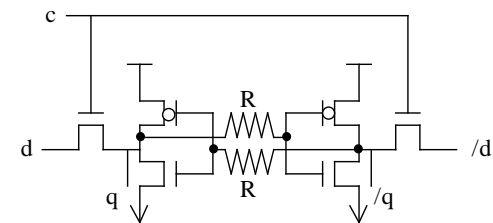
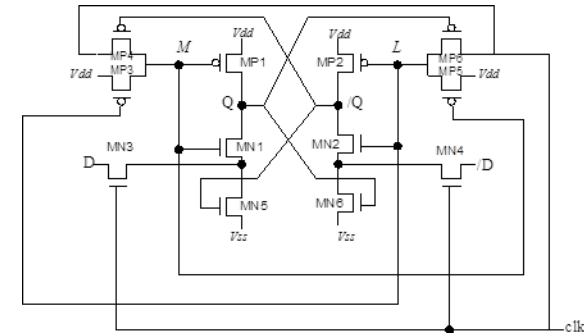
1. The rad-hard version of the Virtex-5QV FPGA has been qualified for high-radiation, deep-space applications.



+ all techniques explained in Chapter 10 (Digital designs)

## 13 Embedded memories

- 13.1 Scope
- 13.2 Table of effects vs mitigation techniques
- 13.3 Mitigation techniques
  - 13.3.1 Resistive hardening
  - 13.3.2 Capacitive hardening
  - 13.3.3 IBM hardened memory cell
  - 13.3.4 HIT hardened memory cell
  - 13.3.5 DICE hardened memory cell
  - 13.3.6 NASA-Whitaker hardened memory cell
  - 13.3.7 NASA-Liu hardened memory cell
  - 13.3.8 Data scrambling



## 14 Embedded software

14.1 Scope

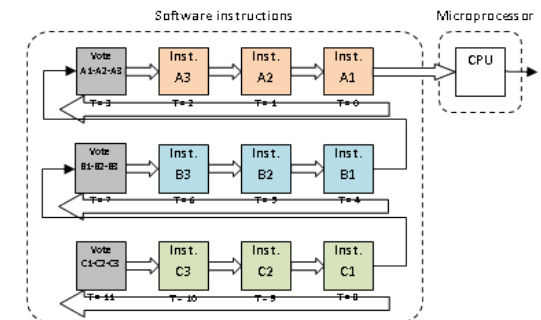
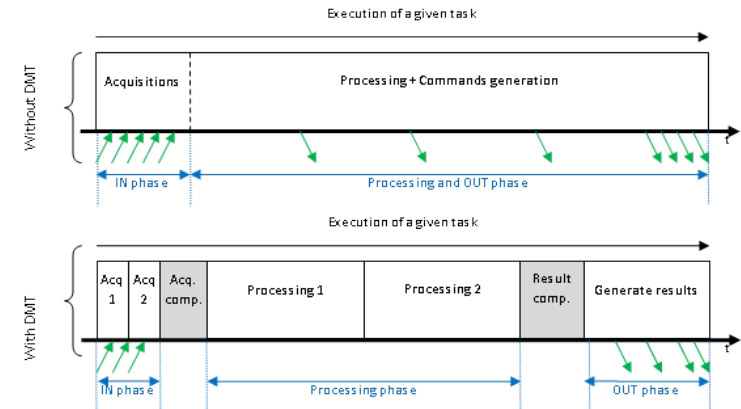
14.2 Table of effects vs mitigation techniques

14.3 Mitigation techniques

14.3.1 Redundancy at instruction level

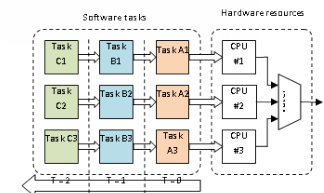
14.3.2 Redundancy at task level

14.3.3 Redundancy at application level

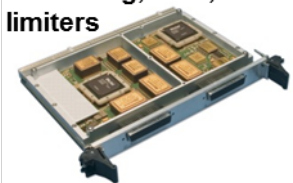


## 15 System architecture

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- 15.2 Table of effects vs mitigation techniques
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  - 15.3.1 Shielding
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- 15.5 Examples of adopted architectures on-board satellites
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scrubbing, TMR, current limiters



## 16 Validation methods

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16.2 Prediction

16.3 Real-life tests

16.4 Ground accelerated tests

16.4.1 Standards and specifications

16.4.2 Test methodologies

16.4.3 Test facilities

16.4.4 Practical constraints

16.4.5 DUT preparation

16.5 Fault injection

16.5.1 Fault injection at transistor level

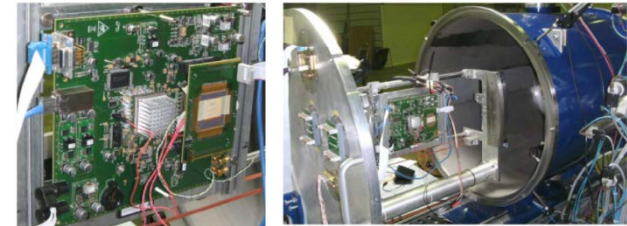
16.5.2 Fault injection at gate level

16.5.3 Fault injection at device level

16.5.4 Fault injection at system level

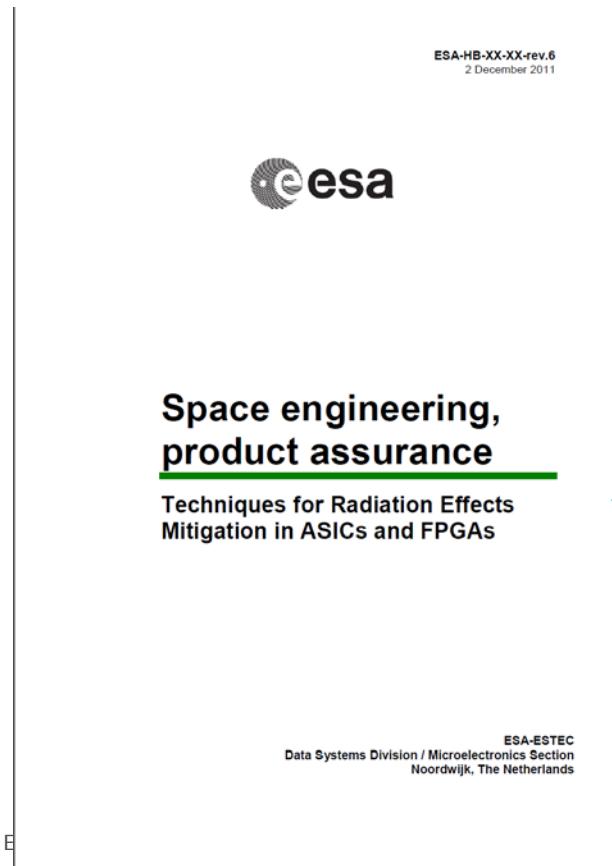
16.6 Analytical methods

- ♦ **Radiation Facilities in use by ESA** <https://escies.org/ReadArticle?docId=230>
  - ▲ Co-60 at ESA/ESTEC, Netherlands (total dose)
  - ▲ Californium-252 at ESA/ESTEC, Netherlands
  - ▲ Paul Scherrer Institut (PSI), Switzerland: proton irradiation
  - ▲ Louvain la Neuve (UCL), Belgium: heavy ions and protons
  - ▲ Jyväskylä University, Finland: heavy ions and protons



**02-Dec-2011** presented at ESTEC, and distributed on-line as .pdf and as a book:

[http://microelectronics.esa.int/handbook/HB\\_Radiation\\_Hardening\\_2011-12-02.pdf](http://microelectronics.esa.int/handbook/HB_Radiation_Hardening_2011-12-02.pdf)



Version 6

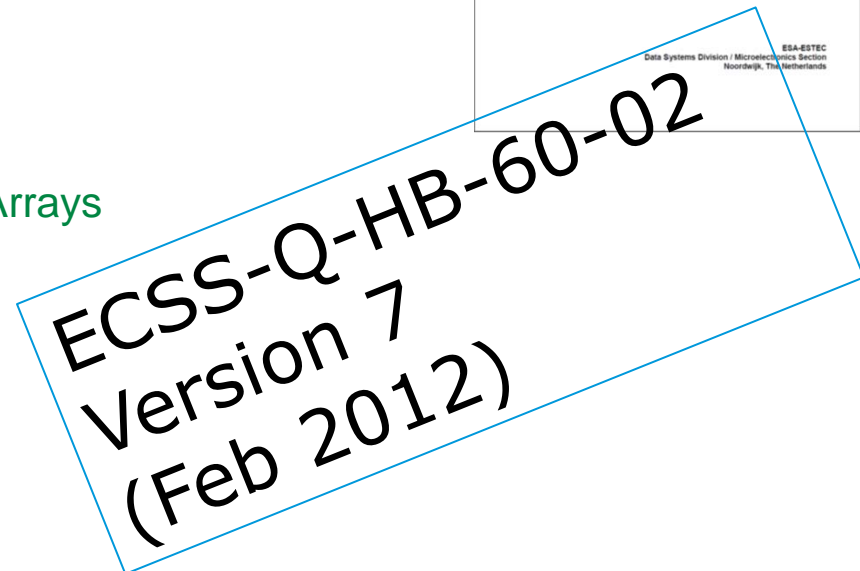
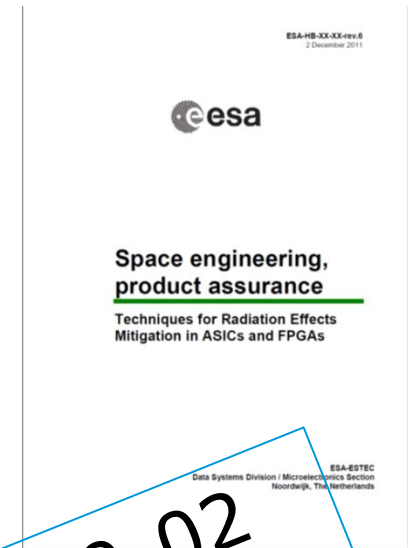


# ECSS HB Working Group starting point:



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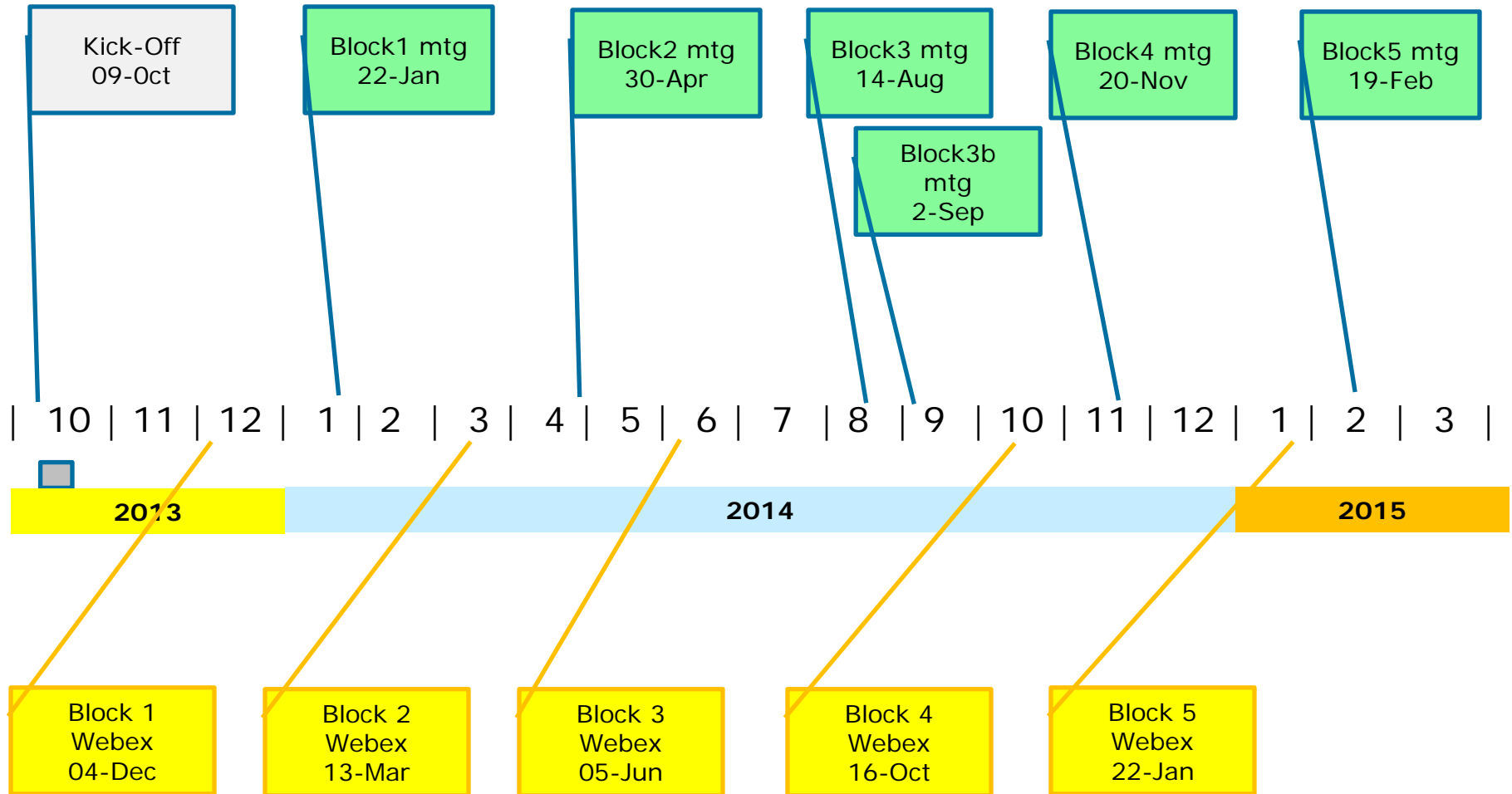
# HB WG review in steps: 5 BLOCKs



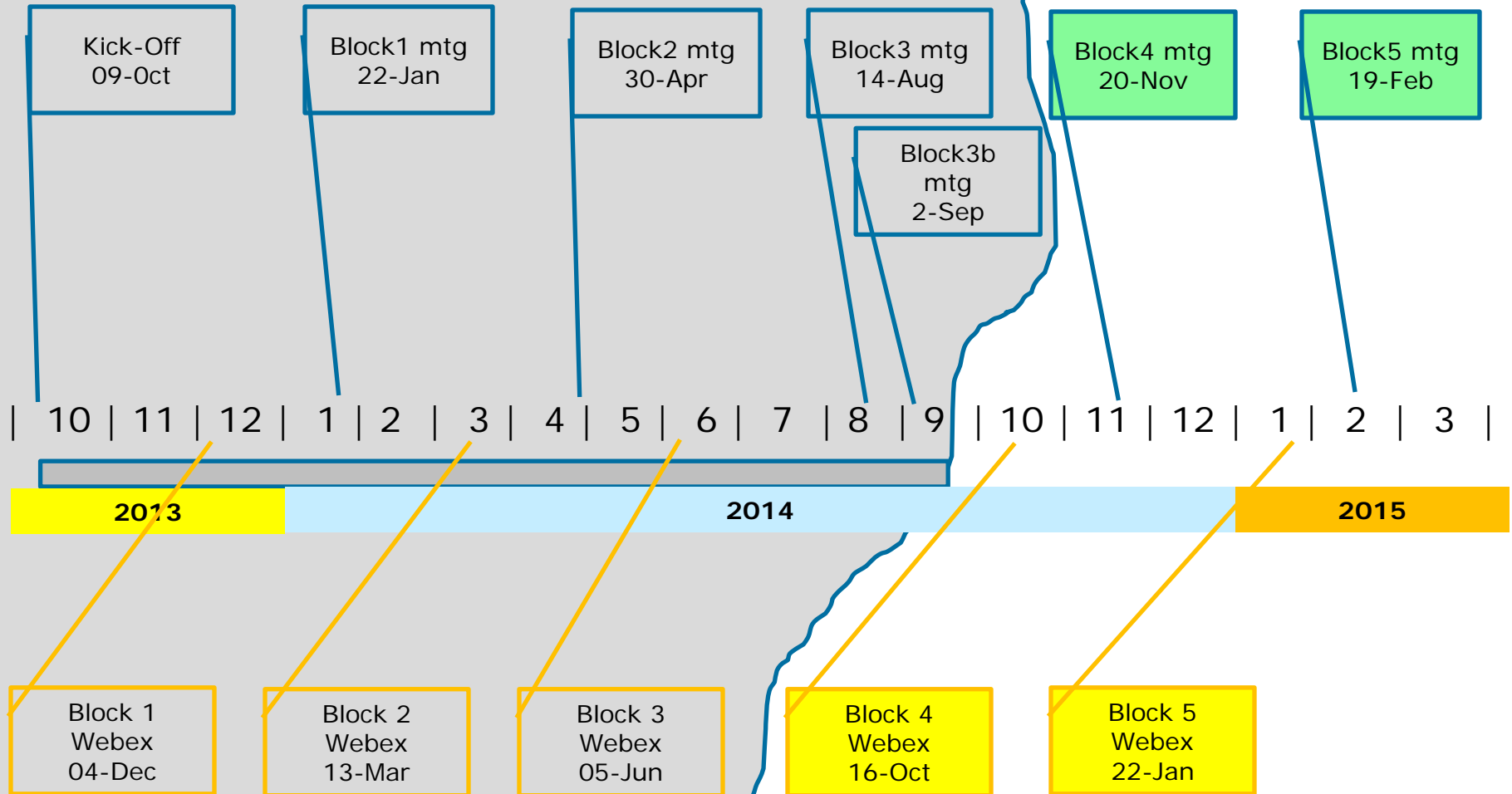
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# HB WG Review plan: 12 meetings, 1.5 yrs

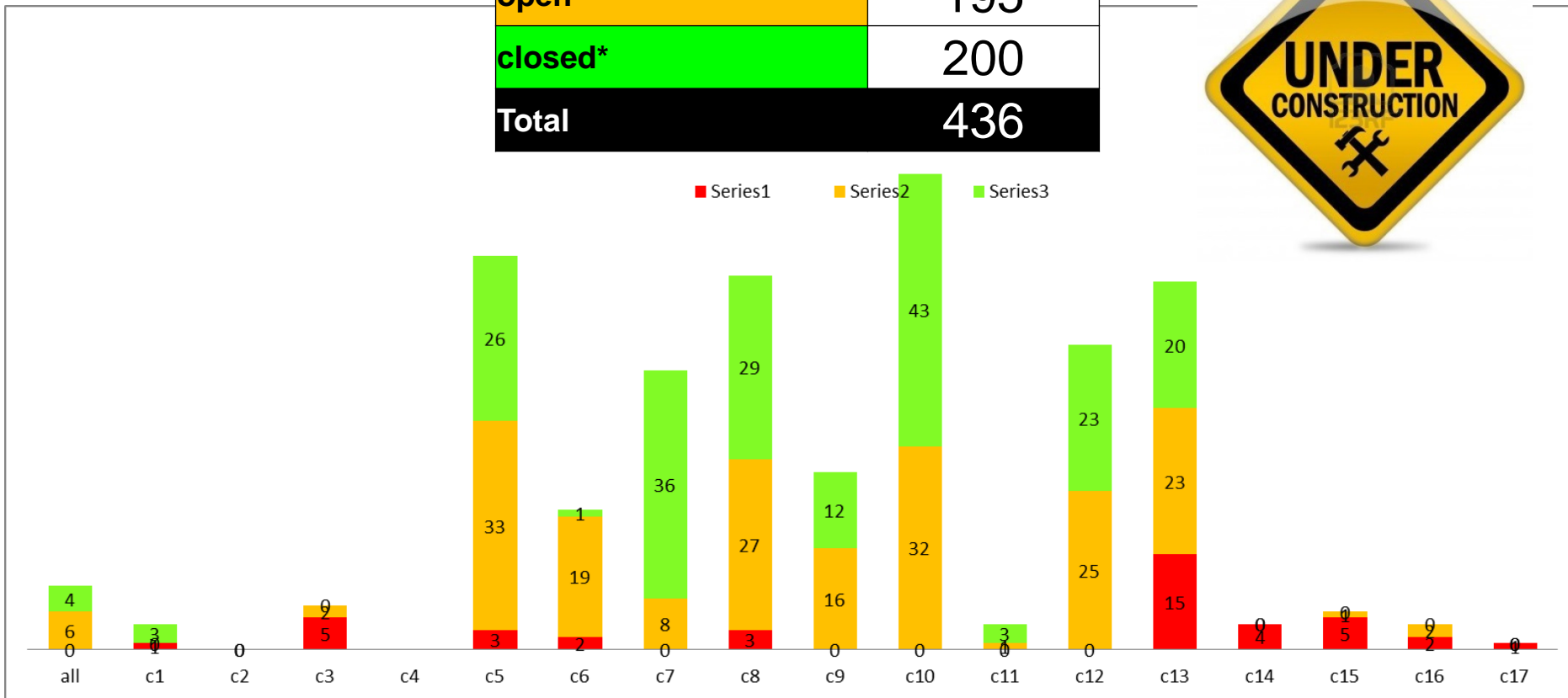


# HB WG Review plan



# “requests for changes” so far by HB WG

not discussed yet	41
open*	195
closed*	200
Total	436



**2014** : ECSS Working Group preparing a new, improved HB draft for ...

→ **Your suggestions welcome !**

**2015/03**: ECSS-Q-HB-60-02 release for ECSS “**public review**”

→ **Your last opportunity to propose changes !!**

**2015/Q3**: ECSS-Q-HB-60-02 **final release** as a new ECSS handbook

# THANKS, Questions? Suggestions?

**ECSS-Q-HB-60-02**

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